

EXPRESS MAIL NO. EV 327 135 248 US

DATE OF DEPOSIT 10/1/03

Our File No. 9281-4702

Client No. S US02113

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Teruyoshi Kubokawa et al.)
Serial No. To be Assigned)
Filing Date: Herewith)
For Solder Joint Structure and Method for)
Soldering Electronic Components)

INFORMATION DISCLOSURE STATEMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Pursuant to the obligation under 37 C.F.R. 1.56 and in conformance with 37 C.F.R. 1.97-1.99, Applicants hereby submit references A1 – A3 listed on the attached form PTO-1449 for consideration by the Examiner. Copies of the references are enclosed herewith.

Japanese Unexamined Patent Application Publication No. 2002-066783 discloses a lead-free soldering method and a mount structure that achieves high reliability after solder-jointing. Japanese Unexamined Patent Application Publication No. 2002-158438 discloses a lead-free solder structure with improved solder joint strength. Japanese Unexamined Patent Application Publication No. 2000-079494 discloses a lead-free solder structure having a low-melting point that achieves improved solder joint strength.

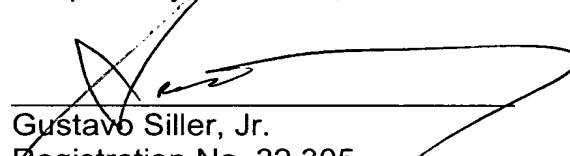
The filing of this Information Disclosure Statement does not constitute an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. Section 1.56(b). Further, Applicants reserve the

right to contest these references as prior art against the present application, and Applicants do not believe that the disclosure of these references, even if finally determined to be prior art, anticipates Applicants' invention or that these references make Applicants' invention obvious.

No fees are believed to be due in connection with filing of this Information Disclosure Statement, however, should any fees under 37 C.F.R. §§ 1.16 to 1.21 be deemed necessary for any reason relating to this material, the Commissioner is hereby authorized to deduct said fees from Brinks Hofer Gilson & Lione Deposit Account No. 23-1925.

Applicants respectfully request that the Examiner review the entire disclosure of these documents and make them of record.

Respectfully submitted,



Gustavo Siller, Jr.
Registration No. 32,305
Attorney for Applicants

BRINKS HOFER GILSON & LIONE
P.O. BOX 10395
CHICAGO, ILLINOIS 60610
(312) 321-4200

FORM PTO-1449 LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (use several sheets if necessary)	SERIAL NO.	CASE NO.
	To be Assigned	9281-4702
	FILING DATE	GROUP ART UNIT
Herewith		
APPLICANTS: Teruyoshi Kubokawa et al.		

REFERENCE DESIGNATION
U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS/ SUBCLASS	FILING DATE

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES	TRANSLATION NO
	A1	Japanese Unexamined Patent Application Publication No. 2002-066783	03/2002	Japan		x
	A2	Japanese Unexamined Patent Application Publication No. 2002-158438	05/2002	Japan		x
	A3	Japanese Unexamined Patent Application Publication No. 2000-079494	03/2000	Japan		x

EXAMINER INITIAL	OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER	DATE CONSIDERED
----------	-----------------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.